

2SC5913

Silicon NPN triple diffusion mesa type

Horizontal deflection output for TV, CRT Monitor

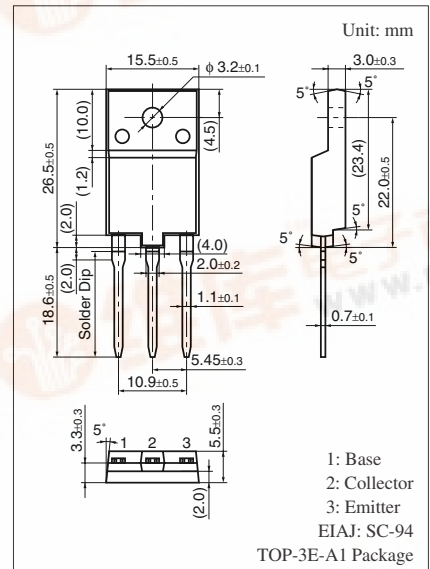
Features

- High breakdown voltage: $V_{CBO} \geq 1\,500\text{ V}$
- Wide safe operation area
- Built-in dumper diode

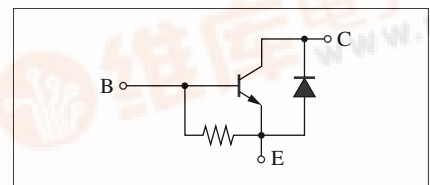
Absolute Maximum Ratings $T_C = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	1 500	V
Collector-emitter voltage (E-B short)	V_{CES}	1 500	V
Emitter-base voltage (Collector open)	V_{EBO}	5	V
Base current	I_B	3	A
Collector current	I_C	6	A
Peak collector current *	I_{CP}	9	A
Collector power dissipation	P_C	40	W
		$T_a = 25^\circ\text{C}$	3
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: Non-repetitive peak collector current



Internal Connection

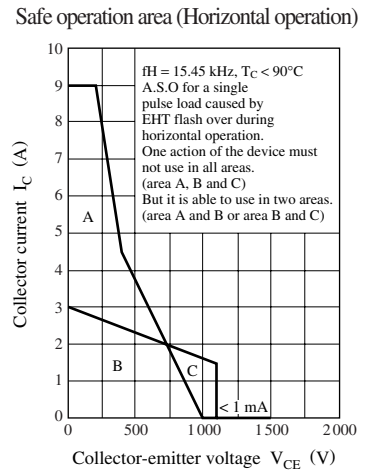
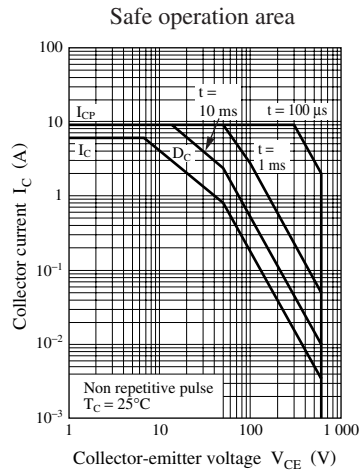
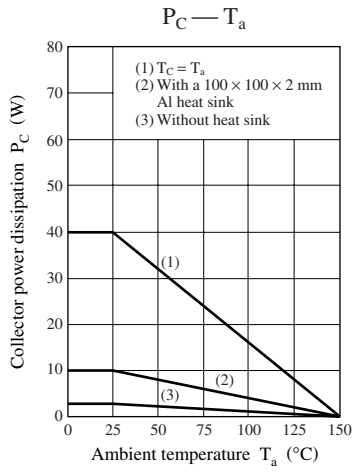


Electrical Characteristics $T_C = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 500\text{ mA}, I_C = 0$	5			V
Forward voltage	V_F	$I_F = 3\text{ A}$			-2	V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 1\,000\text{ V}, I_E = 0$			50	μA
		$V_{CB} = 1\,500\text{ V}, I_E = 0$			1	mA
Forward current transfer ratio	h_{FE}	$V_{CE} = 5\text{ V}, I_C = 3\text{ A}$	5		10	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 3\text{ A}, I_B = 0.75\text{ A}$			2.5	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C = 3\text{ A}, I_B = 0.75\text{ A}$			1.5	V
Transition frequency	f_T	$V_{CE} = 10\text{ V}, I_C = 0.1\text{ A}, f = 0.5\text{ MHz}$		3		MHz
Storage time	t_{stg}	$I_C = 3\text{ A}, \text{Resistance loaded}$			5.0	μs
Fall time	t_f	$I_{B1} = 0.75\text{ A}, I_{B2} = -1.5\text{ A}$			0.5	μs

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.





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